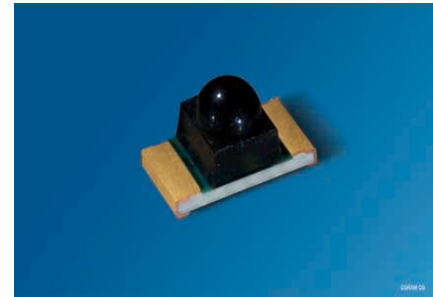


**IR-Lumineszenzdiode (850 nm) mit hoher Ausgangsleistung**  
**High Power Infrared Emitter (850 nm)**  
**Lead (Pb) Free Product - RoHS Compliant**

**SFH 4059**



**Wesentliche Merkmale**

- Sehr kleines Gehäuse:  
(LxBxH) 3.2 mm x 1.6mm x 1.85 mm
- Sehr hohe Gesamtleistung

**Anwendungen**

- Miniaturlichtschranken
- Industrieelektronik
- Mobile Geräte
- „Messen/Steuern/Regeln“

**Sicherheitshinweise**

Je nach Betriebsart emittieren diese Bauteile hochkonzentrierte, nicht sichtbare Infrarot-Strahlung, die gefährlich für das menschliche Auge sein kann. Produkte, die diese Bauteile enthalten, müssen gemäß den Sicherheitsrichtlinien der IEC-Normen 60825-1 und 62471 behandelt werden.

**Features**

- Very small package:  
(LxWxH) 3.2 mm x 1.6 mm x 1.85 mm
- High optical total power

**Applications**

- Miniature photointerrupters
- Industrial electronics
- Mobile devices
- For drive and control circuits

**Safety Advices**

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Typ Type	Bestellnummer Ordering Code	Strahlstärkegruppierung <sup>1)</sup> ( $I_F = 70 \text{ mA}$ , $t_p = 20 \text{ ms}$ ) Radiant Intensity Grouping <sup>1)</sup> $I_e$ (mW/sr)
SFH 4059	Q65111A0020	$\geq 40$ (typ. 100)

<sup>1)</sup> gemessen bei einem Raumwinkel  $\Omega = 0.01 \text{ sr}$  / measured at a solid angle of  $\Omega = 0.01 \text{ sr}$

**Grenzwerte** ( $T_A = 25\text{ °C}$ )**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}, T_{stg}$	- 40 ... + 85	°C
Sperrspannung Reverse voltage	$V_R$	5	V
Vorwärtsgleichstrom Forward current	$I_F$	70	mA
Stoßstrom, $t_p = 10\text{ }\mu\text{s}$ , $D = 0$ Surge current	$I_{FSM}$	700	mA
Verlustleistung Power dissipation	$P_{tot}$	140	mW
Wärmewiderstand Sperrschicht - Umgebung bei Montage auf FR4 Platine, Padgröße je $5\text{ mm}^2$ Thermal resistance junction - ambient mounted on PC-board (FR4), padsize $5\text{ mm}^2$ each	$R_{thJA}$	540	K/W
Wärmewiderstand Sperrschicht - Lötstelle bei Montage auf Metallkernplatine Thermal resistance junction - soldering point, mounted on metal core board	$R_{thJS}$	360	K/W

**Kennwerte** ( $T_A = 25\text{ °C}$ )**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission $I_F = 70\text{ mA}$ , $t_p = 10\text{ ms}$	$\lambda_{peak}$	860	nm
Schwerpunkts-Wellenlänge der Strahlung Centroid Wavelength $I_F = 70\text{ mA}$ , $t_p = 10\text{ ms}$	$\lambda_{centroid}$	850	nm
Spektrale Bandbreite bei 50% von $I_{max}$ Spectral bandwidth at 50% of $I_{max}$ $I_F = 70\text{ mA}$ , $t_p = 10\text{ ms}$	$\Delta\lambda$	42	nm
Abstrahlwinkel Half angle	$\varphi$	$\pm 10$	Grad deg.
Aktive Chipfläche Active chip area	$A$	0.04	$\text{mm}^2$

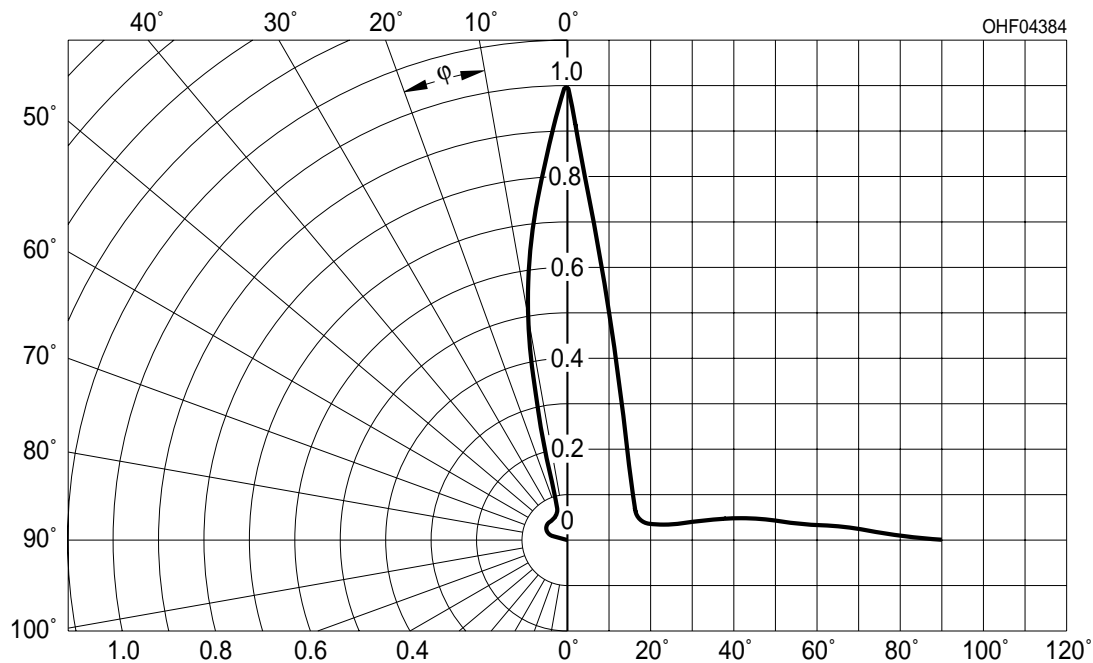
**Kennwerte** ( $T_A = 25\text{ °C}$ )  
**Characteristics** (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B$ $L \times W$	$0.2 \times 0.2$	mm <sup>2</sup>
Schaltzeiten, $I_e$ von 10% auf 90% und von 90% auf 10%, bei $I_F = 70\text{ mA}$ , $R_L = 50\ \Omega$ Switching times, $I_e$ from 10% to 90% and from 90% to 10%, $I_F = 70\text{ mA}$ , $R_L = 50\ \Omega$	$t_r$ , $t_f$	12	ns
Durchlassspannung Forward voltage $I_F = 70\text{ mA}$ , $t_p = 20\text{ ms}$	$V_F$	1.6 (< 2.0)	V
Sperrstrom Reverse current	$I_R$	not designed for reverse operation	$\mu\text{A}$
Gesamtstrahlungsfluss Total radiant flux $I_F = 70\text{ mA}$ , $t_p = 20\text{ ms}$	$\Phi_{e\text{ typ}}$	40	mW
Temperaturkoeffizient von $I_e$ bzw. $\Phi_e$ , $I_F = 70\text{ mA}$ Temperature coefficient of $I_e$ or $\Phi_e$ , $I_F = 70\text{ mA}$	$TC_I$	- 0.5	%/K
Temperaturkoeffizient von $V_F$ , $I_F = 70\text{ mA}$ Temperature coefficient of $V_F$ , $I_F = 70\text{ mA}$	$TC_V$	- 0.7	mV/K
Temperaturkoeffizient von $\lambda$ , $I_F = 70\text{ mA}$ Temperature coefficient of $\lambda$ , $I_F = 70\text{ mA}$	$TC_\lambda$	+ 0.3	nm/K

**Strahlstärke  $I_e$  in Achsrichtung<sup>1)</sup>**gemessen bei einem Raumwinkel  $\Omega = 0.01$  sr**Radiant Intensity  $I_e$  in Axial Direction**at a solid angle of  $\Omega = 0.01$  sr

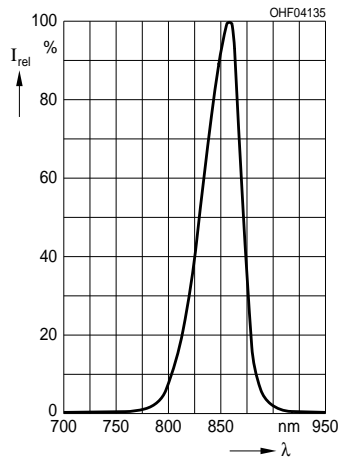
Bezeichnung Parameter	Symbol	Werte Values			Einheit Unit
		SFH 4059 -U	SFH 4059 -V	SFH 4059 -AW	
Strahlstärke Radiant intensity $I_F = 70$ mA, $t_p = 20$ ms	$I_{e \min}$ $I_{e \max}$	40 80	63 125	100 200	mW/sr mW/sr
Strahlstärke Radiant intensity $I_F = 500$ mA, $t_p = 25$ $\mu$ s	$I_{e \text{ typ}}$	350	550	900	mW/sr

<sup>1)</sup> Nur eine Gruppe in einer Verpackungseinheit (Streuung kleiner 2:1) /  
Only one bin in one packing unit (variation lower 2:1)

**Abstrahlcharakteristik****Radiation Characteristics  $I_{\text{rel}} = f(\varphi)$** 

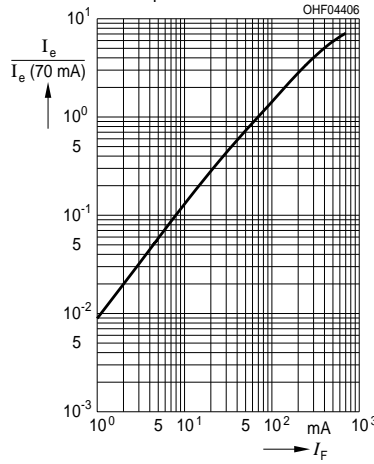
**Relative Spectral Emission**

$I_{rel} = f(\lambda)$



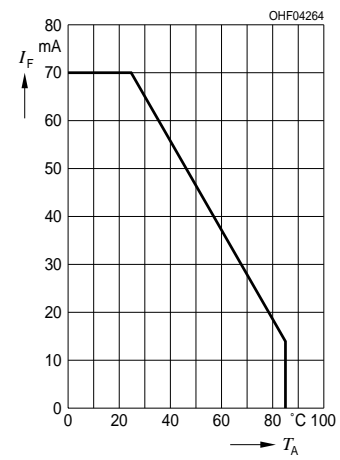
**Radiant Intensity**  $\frac{I_e}{I_e(70 \text{ mA})} = f(I_F)$

Single pulse,  $t_p = 25 \mu\text{s}$



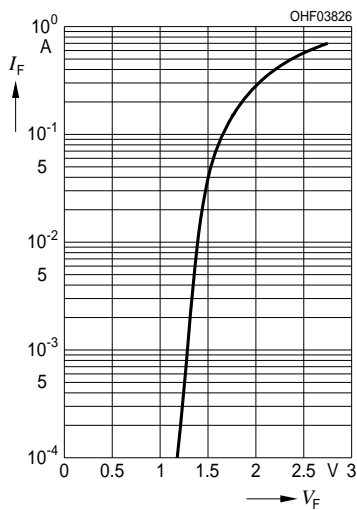
**Max. Permissible Forward Current**

$I_F = f(T_A), R_{thJA} = 540\text{K/W}$

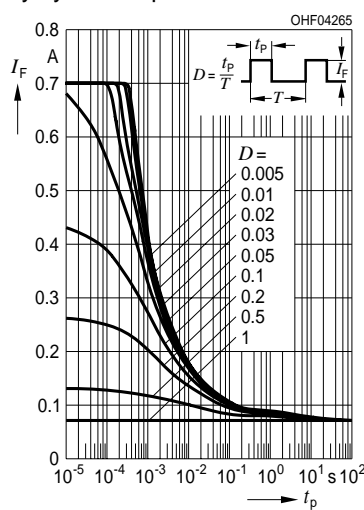


**Forward Current**  $I_F = f(V_F)$

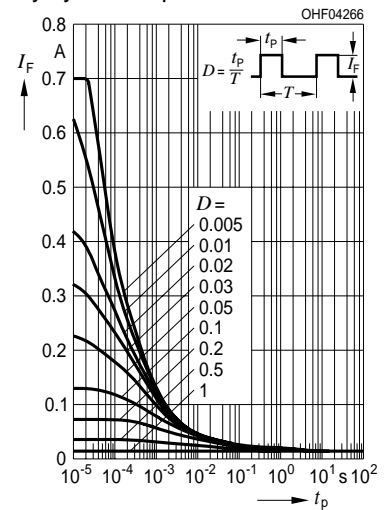
Single pulse,  $t_p = 100 \mu\text{s}$

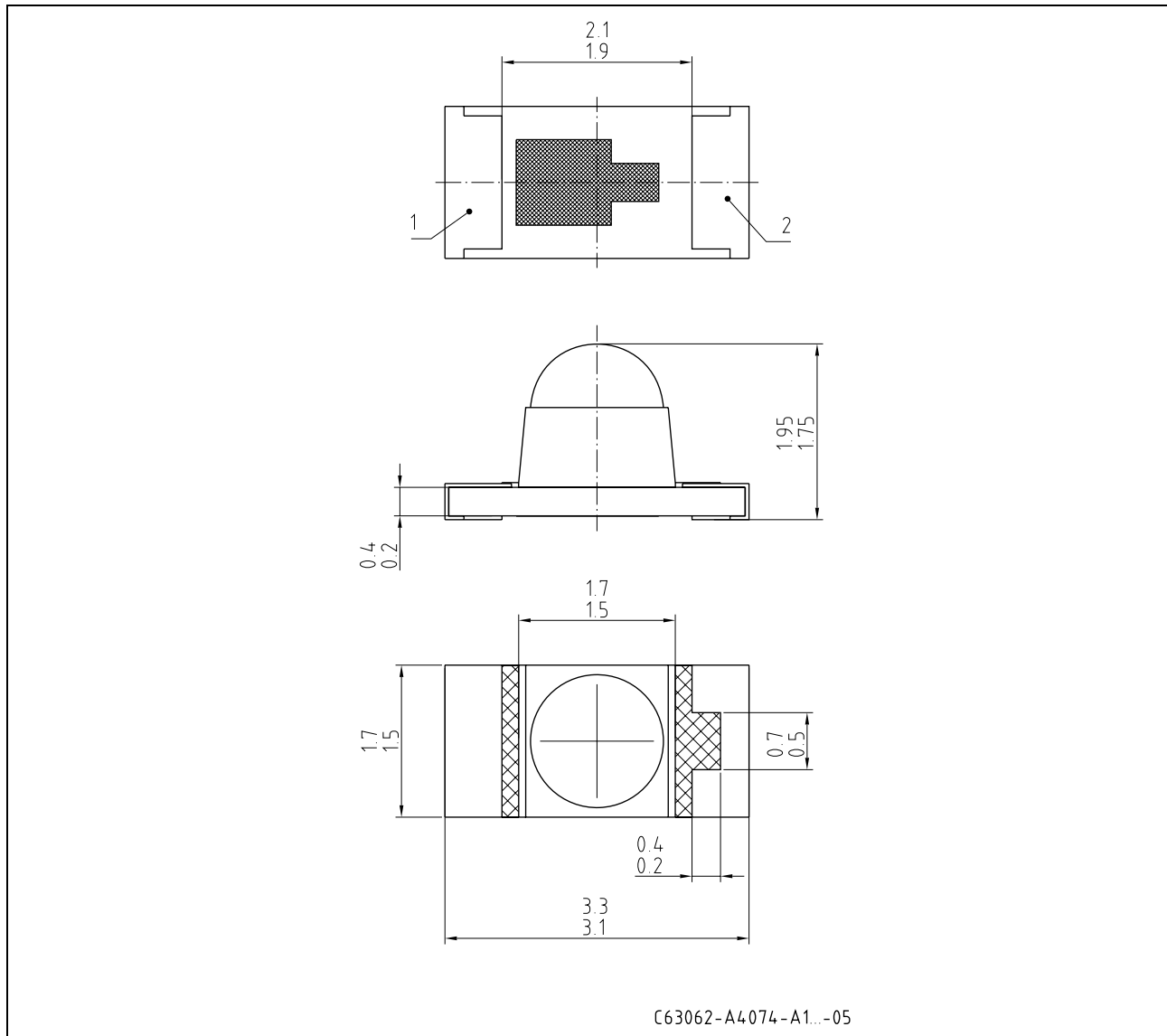


**Permissible Pulse Handling Capability**  $I_F = f(\tau), T_A = 25^\circ\text{C}$ , duty cycle  $D = \text{parameter}$



**Permissible Pulse Handling Capability**  $I_F = f(\tau), T_A = 85^\circ\text{C}$ , duty cycle  $D = \text{parameter}$



**Maßzeichnung**  
**Package Outlines**


Maße in mm/ Dimensions in mm.

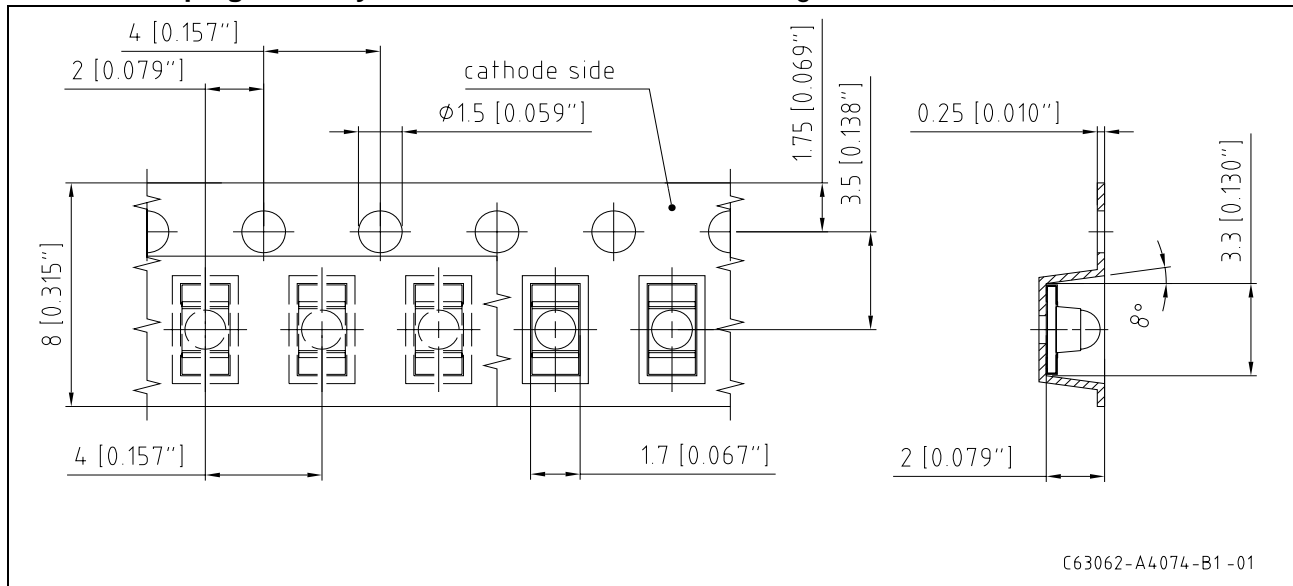
Gehäuse / Package	Epoxydharz / Epoxy
Farbe / Colour	Schwarz / black
Gehäusemarkierung/ Package marking	Pad 1: Kathode / cathode Pad 2: Anode / anode

**Gurtung / Polarität und Lage**

Verpackungseinheit 2000/Rolle, ø180 mm

**Method of Taping / Polarity and Orientation**

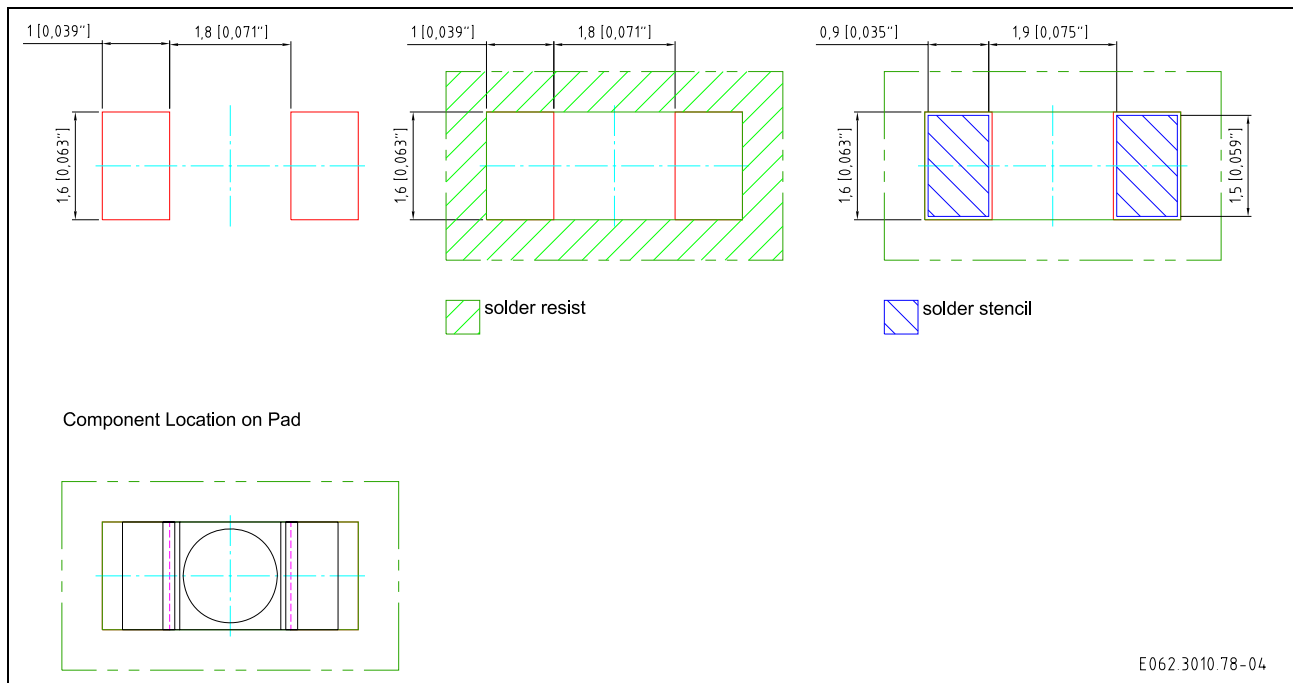
Packing unit 2000/reel, ø180 mm



Maße in mm (inch) / Dimensions in mm (inch).

**Empfohlenes Lötpad-Design  
Recommended Solder Pad**

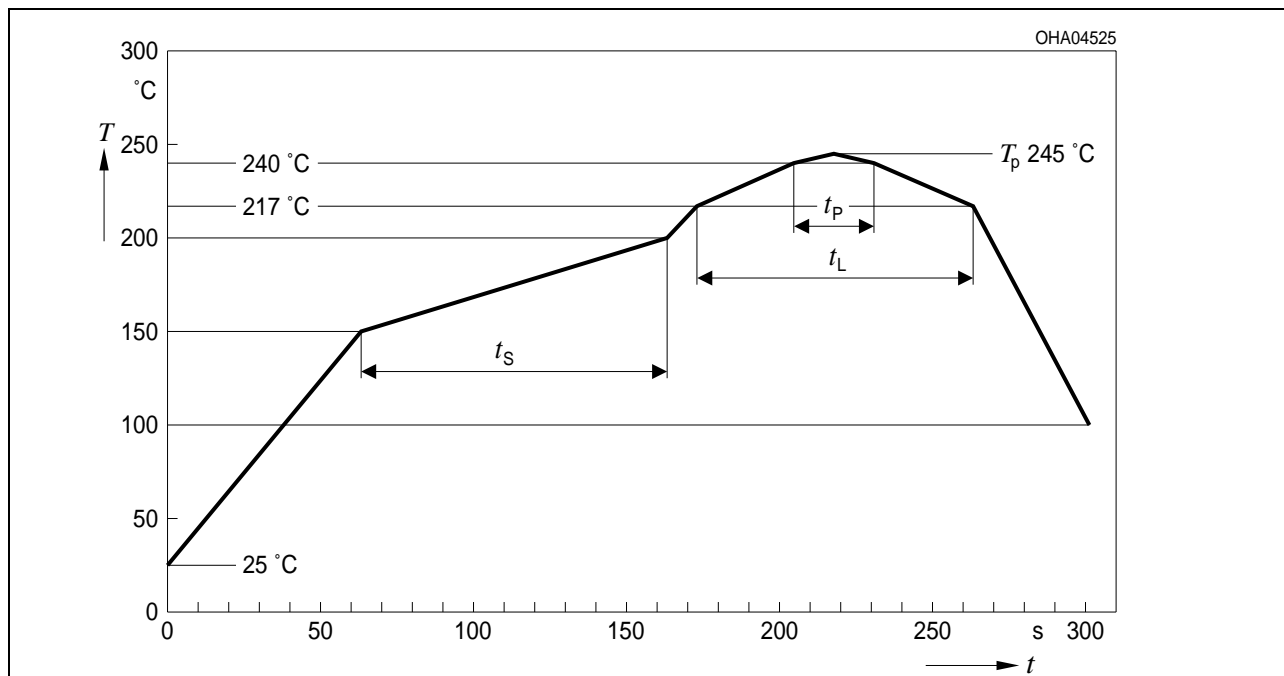
**Reflow Löten  
Reflow Soldering**



Maße in mm / Dimensions in mm (inch).

**Lötbedingungen**  
**Soldering Conditions**  
**Reflow Lötprofil für bleifreies Löt**  
**Reflow Soldering Profile for lead free soldering**

Vorbehandlung nach JEDEC Level 3  
 Preconditioning acc. to JEDEC Level 3  
 (nach J-STD-020-D.01)  
 (acc. to J-STD-020-D.01)



Pb-Free (SnAgCu) Assembly		
Profile Feature	Recommendation	Max. Ratings
Ramp-up Rate to Preheat*) 25°C to 150°C	2°C / sec	3°C / sec
Time $t_s$ from $T_{Smin}$ to $T_{Smax}$ (150°C to 200°C)	100s	min. 60sec max. 120sec
Ramp-up Rate to Peak*) $T_{Smax}$ to $T_p$	2°C / sec	3°C / sec
Liquidus Temperature $T_L$	217°C	
Time $t_L$ above $T_L$	80sec	max. 100sec
Peak Temperature $T_p$	245°C	max. 260°C
Time $t_p$ within 5°C of the specified peak temperature $T_p - 5K$	20sec	min. 10sec max. 30sec
Ramp-down Rate* $T_p$ to 100°C	3°C / sec	6°C / sec maximum
Time 25°C to Peak temperature		max. 8 min.

All temperatures refer to the center of the package, measured on the top of the component

\* slope calculation  $\Delta T/\Delta t$ :  $\Delta t$  max. 5 sec; fulfillment for the whole T-range



Published by  
OSRAM Opto Semiconductors GmbH  
Leibnizstrasse 4, D-93055 Regensburg  
[www.osram-os.com](http://www.osram-os.com)

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<sup>1</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

<sup>2</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.

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